

ABSTRACT

A circuit board (1) includes a substrate (2) including electrode patterns (22) formed thereon, first chip components (3a, 3b) mounted on the substrate and a second chip component (4) mounted on a side of electrodes of the first chip components opposite from the substrate. The second chip component is bonded at one electrode (41) to an electrode (31) of the first chip component and is also bonded at the other electrode (41) to an electrode (31) of the first chip component. By stacking chip components in plural stages, it is possible to mount chip components with a high density on the substrate, thereby enabling reduction of the size of the circuit board.